

Electronic Patent Application Fee Transmittal

Application Number:	10789637			
Filing Date:	27-Feb-2004			
Title of Invention:	Flip chip semiconductor die internal signal access system and method			
First Named Inventor/Applicant Name:	Brian S. Schieck			
Filer:	John F. Ryan			
Attorney Docket Number:	NVID-P001125			

Filed as Large Entity

Utility under 35 USC 111(a) Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Extension-of-Time:

Extension - 1 month with \$0 paid	1251	1	120	120
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				930